

Product Change Notification - JAON-19VEXA051

Date:

27 Dec 2018

Product Category:

32-bit Microcontrollers; Wireless Modules; Smart Energy Wireless Communications

Affected CPNs:

7

Notification subject:

CCB 3654 Initial Notice: Qualification of MMT as an additional assembly site for selected Atmel products of 58.5K and 58.85K wafer technologies available in 48L VQFN (7x7x0.9mm) package.

Notification text:

PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of MMT as an additional assembly site for selected Atmel products of 58.5K and 58.85K wafer technologies available in 48L VQFN (7x7x0.9mm) package.

Pre-Change:

Assembled at ASE using palladium coated copper (PdCu) bond wire, EN-4900F die attach and G631H mold compound material or assembled at ATP7 using gold palladium (AuPd) bond wire, AMK-06 die attach and G700 mold compound material

Post Change:

Assembled at ASE using palladium coated copper (PdCu) bond wire, EN-4900F die attach and G631H mold compound material or assembled at ATP7 using gold palladium (AuPd) bond wire, AMK-06 die attach and G700 mold compound material or assembled at MMT using gold (Au) bond wire, 3280 die attach and G700 mold compound material.

	Pre C	hange	Post Change				
Assembly Site	ASE Inc. (ASE)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	ASE Inc. (ASE)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Microchip Technology Thailand (Branch) (MMT)		
Wire material	PdCu	AuPd	PdCu	AuPd	Au		
Die attach material	EN-4900F	AMK-06	EN-4900F	AMK-06	3280		
Molding compound material	G631H	G700	G631H	G700	G700		
Lead frame material	C194	C194	C194	C194	C194		
MSL level	MSL 3	MSL 3	MSL 3	MSL 3	MSL 1		

Pre and Post Change Summary:

Impacts to Data Sheet:

Yes. POD (package outline drawing) change. See the changes below

<u> </u>	<u> </u>
Pre Change	Post Change
r le change	i ust change



Dimension Limit (in mm)	Min	Nor	Max	Min	Nor	Max	
Number of terminals	48			48			
Overall Height	0.80	0.85	0.90	0.80	0.90	1.00	
Standoff	0.00	0.02	0.05	0.00	-	0.05	
Terminal Thickness	0.20 REF			0.20 REF			
Overall Length	7.00 BSC			7.00 BSC			
Exposed Pad Length	5.50	5.60	5.70		5.60	5.70	
Overall Width	7.00 BSC 7.00 BSC			С			
Exposed Pad Width	5.50	5.60	5.70	5.50	5.60	5.70	
Terminal Width	0.17	0.25	0.30	0.20	0.25	0.30	
Terminal Length	0.30	0.40	0.50	0.30	0.40	0.50	
Pitch	0.50 BCS 0.50 BCS			S			

Change Impact:

None

Reason for Change:

To improve productivity and on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

March 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:



	December 2018				March 2019					
Workweek	49	50	51	52	>	9	10	11	12	13
Initial PCN Issue Date				Х						
Qual Report Availability								Х		
Final PCN Issue Date								Х		

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

December 27, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-19VEXA051_Qual_Plan.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. JAON-19VEXA051 - CCB 3654 Initial Notice: Qualification of MMT as an additional assembly site for selected Atmel products of 58.5K and 58.85K wafer technologies available in 48L VQFN (7x7x0.9mm) package.

Affected Catalog Part Numbers (CPN)

AT86RF215IQ-ZU AT86RF215IQ-ZU-003 AT86RF215IQ-ZU-004 AT86RF215IQ-ZUR AT86RF215IQ-ZUR-003 AT86RF215IQ-ZUR-004 AT86RF215M-ZU AT86RF215M-ZUR AT86RF215-ZU AT86RF215-ZU-003 AT86RF215-ZU-004 AT86RF215-ZUR003 AT86RF215-ZUR004 ATMEGA1284RFR2-ZF ATMEGA1284RFR2-ZFR ATMEGA1284RFR2-ZU ATMEGA1284RFR2-ZUR ATMEGA2564RFR2-ZF ATMEGA2564RFR2-ZFR ATMEGA2564RFR2-ZFRP01 ATMEGA2564RFR2-ZU ATMEGA2564RFR2-ZUR ATMEGA644RFR2-ZF ATMEGA644RFR2-ZFR ATMEGA644RFR2-ZU ATMEGA644RFR2-ZUR ATSAM4LC8AA-MU ATSAM4LC8AA-MUR ATSAM4LS8AA-MU ATSAM4LS8AA-MUR